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STTH3002

Ultrafast recovery diode

Main product characteristics

$I_{F(AV)}$	30 A
V_{RRM}	200 V
T_j (max)	175° C
V_F (typ)	0.77 V
t_{rr} (typ)	22 ns

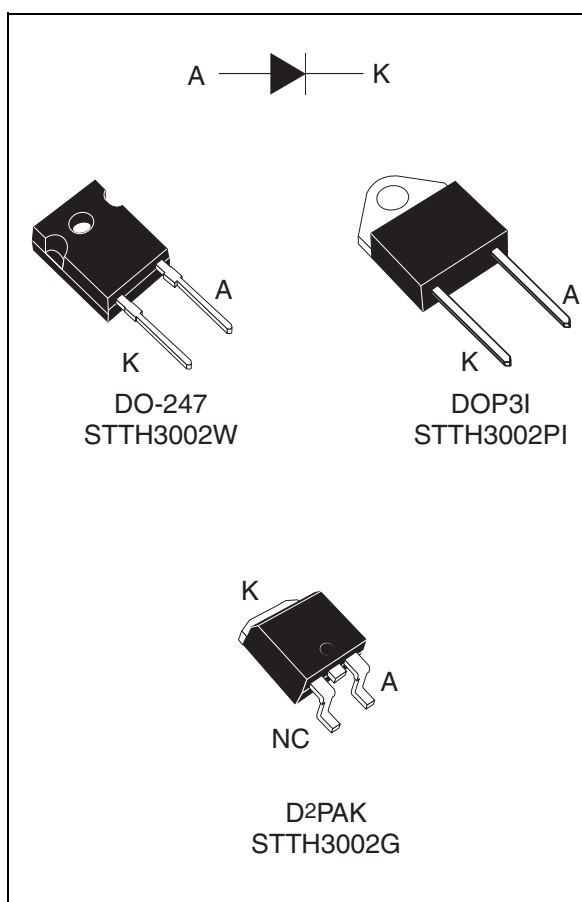
Features and benefits

- Very low conduction losses
- Negligible switching losses
- Low forward and reverse recovery time
- High junction temperature

Description

The STTH3002 uses ST's new 200 V planar Pt doping technology, and is specially suited for switching mode base drive and transistor circuits.

Packaged in DO-247, DOP3I, and D²PAK, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection.



Order codes

Part Number	Marking
STTH3002W	STTH3002
STTH3002PI	STTH3002
STTH3002G	STTH3002
STTH3002G-TR	STTH3002

Characteristics

STTH3002

1 Characteristics

Table 1. Absolute ratings (limiting values at $T_j = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		200	V
$I_{F(RMS)}$	RMS forward current		50	A
$I_{F(AV)}$	Average forward current, $\delta = 0.5$	DO-247 $T_c = 135^\circ\text{C}$	30	A
		DOP3I $T_c = 115^\circ\text{C}$		
		D ² PAK $T_c = 135^\circ\text{C}$		
I_{FSM}	Surge non repetitive forward current	$t_p = 10\text{ ms Sinusoidal}$	300	A
T_{stg}	Storage temperature range		-65 to + 175	$^\circ\text{C}$
T_j	Maximum operating junction temperature		175	$^\circ\text{C}$

Table 2. Thermal parameters

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	DO-247	1.2	$^\circ\text{C/W}$
		DOP3I	1.8	
		D ² PAK	1.2	

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			20	μA
		$T_j = 150^\circ\text{C}$			20	200	
$V_F^{(2)}$	Forward voltage drop	$T_j = 125^\circ\text{C}$	$I_F = 25\text{ A}$		0.77	0.85	V
		$T_j = 25^\circ\text{C}$	$I_F = 30\text{ A}$			1.05	
		$T_j = 150^\circ\text{C}$			0.8	0.88	

1. Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$

2. Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.67 \times I_{F(AV)} + 0.007 I_{F(RMS)}^2$$

STTH3002

Characteristics

Table 4. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ	Max.	Unit
t_{rr}	Reverse recovery time	$I_F = 1\text{ A}$, $di_F/dt = -200\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$, $T_j = 25\text{ }^\circ\text{C}$		22	27	ns
		$I_F = 1\text{ A}$, $di_F/dt = -50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$, $T_j = 25\text{ }^\circ\text{C}$		40	50	
I_{RM}	Reverse recovery current	$I_F = 30\text{ A}$, $di_F/dt = 200\text{ A}/\mu\text{s}$, $V_R = 160\text{ V}$, $T_j = 125\text{ }^\circ\text{C}$		7.6	9.5	A
t_{fr}	Forward recovery time	$I_F = 30\text{ A}$, $di_F/dt = 200\text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$, $T_j = 25\text{ }^\circ\text{C}$		140		ns
V_{FP}	Forward recovery voltage	$I_F = 30\text{ A}$, $di_F/dt = 200\text{ A}/\mu\text{s}$, $V_{FR} = 1.1 \times V_{Fmax}$, $T_j = 25\text{ }^\circ\text{C}$		2.5		V

Figure 1. Peak current versus duty cycle

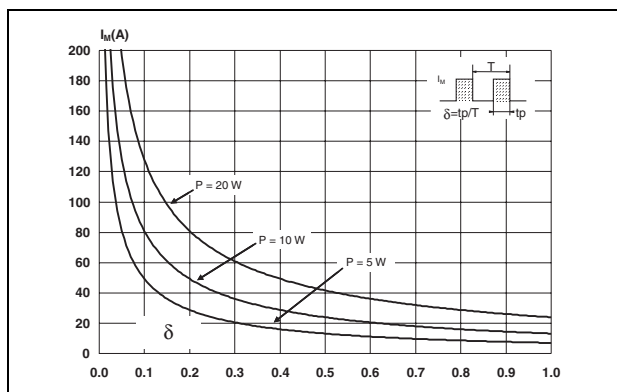


Figure 2. Forward voltage drop versus forward current (typical values)

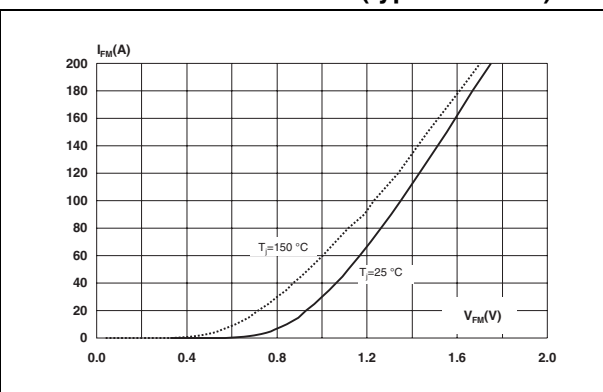


Figure 3. Forward voltage drop versus forward current (maximum values)

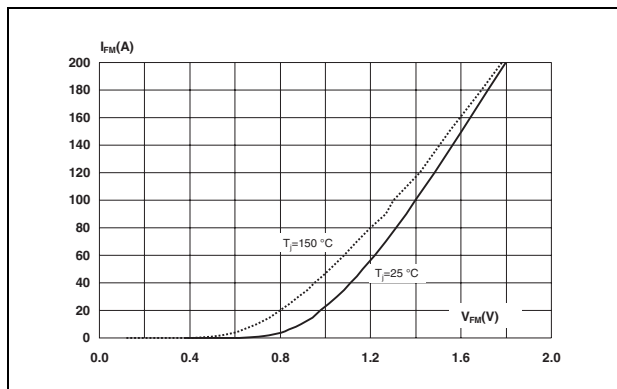
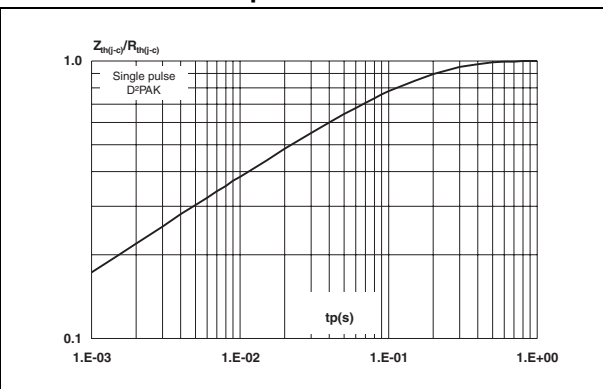


Figure 4. Relative variation of thermal impedance, junction to case, versus pulse duration



Characteristics

STTH3002

Figure 5. Junction capacitance versus reverse voltage applied (typical values)

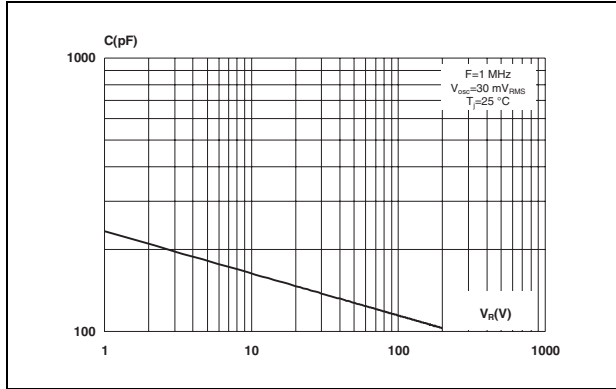


Figure 6. Reverse recovery charges versus di_F/dt (typical values)

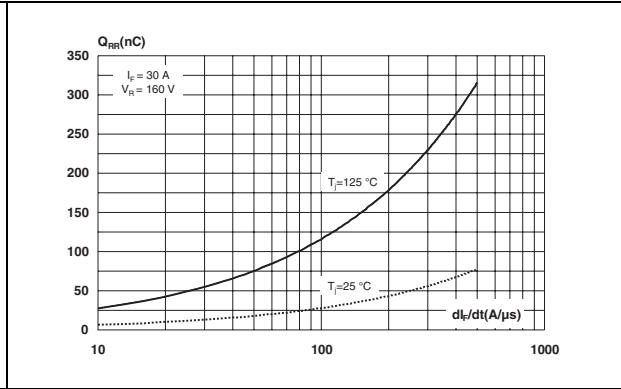


Figure 7. Reverse recovery time versus di_F/dt (typical values)

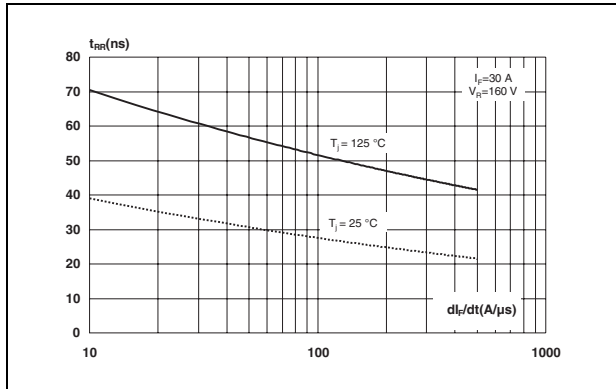


Figure 8. Peak reverse recovery current versus di_F/dt (typical values)

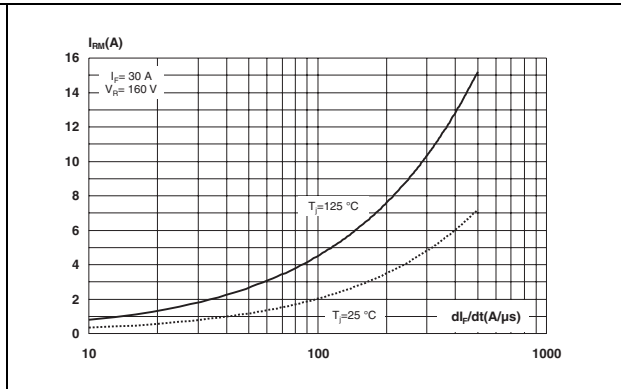


Figure 9. Dynamic parameters versus junction temperature

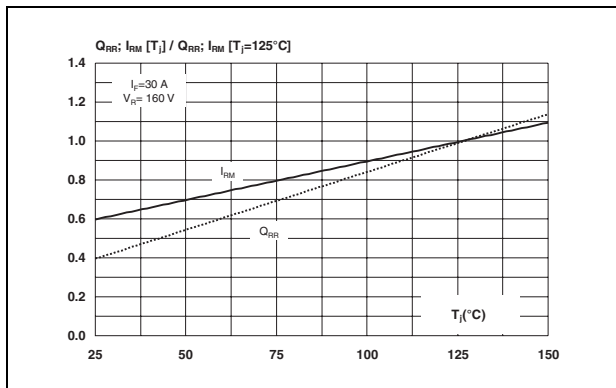
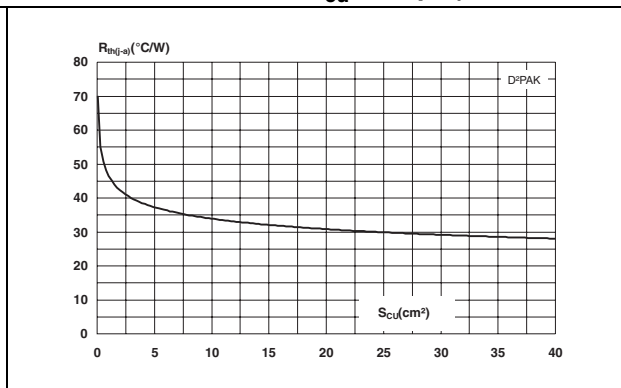


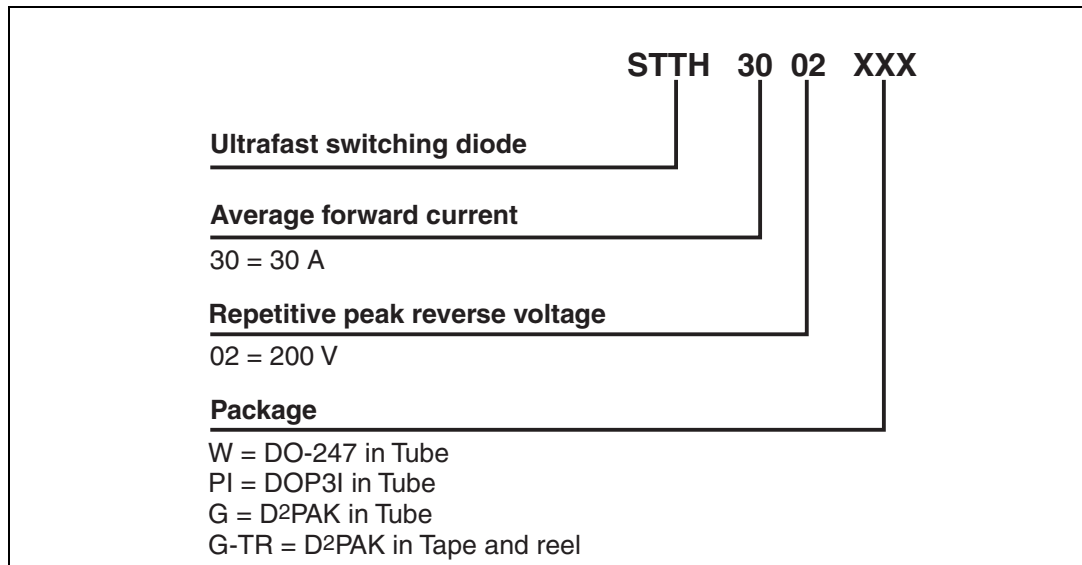
Figure 10. Thermal resistance, junction to ambient, versus copper surface under tab (Epoxy printed circuit board FR4, $e_{Cu} = 35 \mu m$)



STTH3002

Ordering information scheme

2 Ordering information scheme



Package information

STTH3002

3 Package information

Epoxy meets UL94, V0

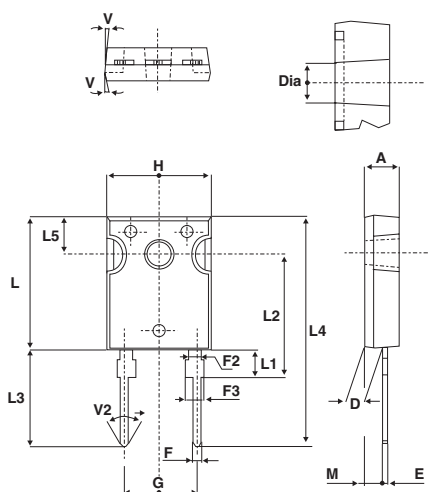
Cooling method: by conduction (C)

Recommended torque value: 0.8 Nm

Maximum torque value: 1.0 Nm

Table 5. DO-247 dimensions

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.15	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F2		2.00			0.078	
F3	2.00		2.40	0.078		0.094
G		10.90			0.429	
H	15.45		15.75	0.608		0.620
L	19.85		20.15	0.781		0.793
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
L3	14.20		14.80	0.559		0.582
L4		34.60			1.362	
L5		5.50			0.216	
M	2.00		3.00	0.078		0.118
V		5°			5°	
V2		60°			60°	
Dia.	3.55		3.65	0.139		0.143



STTH3002

Package information

Table 6. DOP3I dimensions

REF	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
b	1.20	1.40	0.047	0.055
c	1.45	1.55	0.057	0.061
c1	0.50	0.70	0.020	0.028
D	12.15	13.10	0.474	0.516
E	15.10	15.50	0.594	0.610
E1	7.55	7.75	0.297	0.305
e	10.80	11.30	0.425	0.445
G	20.4	21.10	0.815	0.831
L	14.35	15.60	0.565	0.614
P	4.08	4.17	0.161	0.164
Q	2.70	2.90	0.106	0.114
R	4.60 typ.		0.181 typ.	
Y	15.80	16.50	0.622	0.650

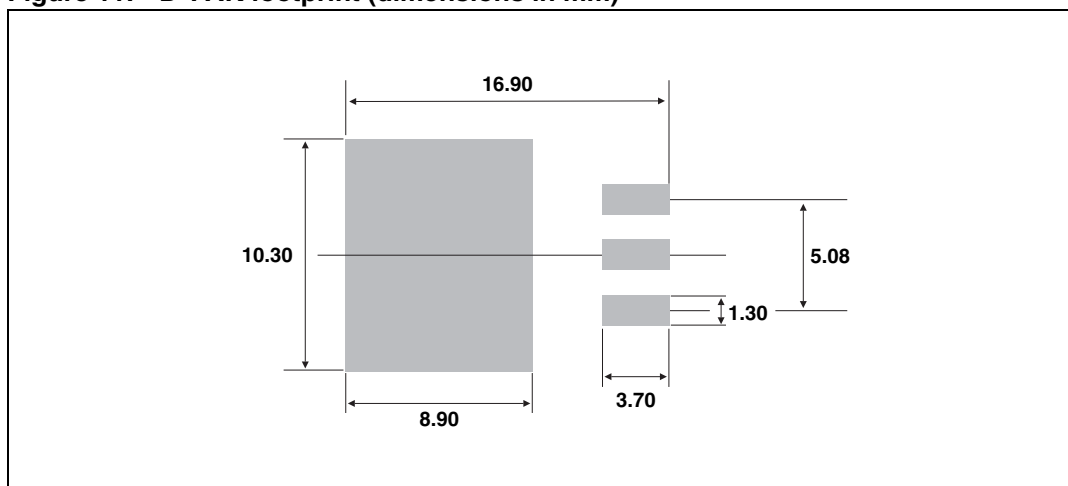
Package information

STTH3002

Table 7. D²PAK dimensions

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

Figure 11. D²PAK footprint (dimensions in mm)



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

STTH3002

Ordering information

4 Ordering information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
STTH3002W	STTH3002	DO-247	4.4 g	30	Tube
STTH3002PI	STTH3002	DOP3I	4.46 g	30	Tube
STTH3002G	STTH3002	D ² PAK	1.48 g	50	Tube
STTH3002G-TR	STTH3002	D ² PAK	1.48 g	1000	Tape and reel

5 Revision history

Date	Revision	Description of Changes
03-May-2006	1	First issue

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